head or of ~~an intermediate~~a connection board, the contact areas each being electrically conductively connected to the corresponding contact sockets.

The operating costs can be considerably lowered by the use of contact sockets instead of contact pins. Since contact sockets at least do not protrude far beyond the surface of the adapter board, the risk that these will be damaged is much lower than with contact pins.

Further details and advantages of the invention will emerge from the dependent claims.

The positions of the contact areas on one side of the adapter board are advantageously arranged independently of the positions of the corresponding contact sockets on the opposite side of the adapter board. In this context, this means, independently, that the positions of corresponding contact areas and contact sockets can be arranged directly above one another or offset in relation to one another. The positions of the contact areas can thus be easily adapted to the positions of the contacts of the test base, and the positions of the contact sockets can be easily adapted to the positions of the contact pins of the test head or of an intermediate board.

As already mentioned above, the positions of the contact areas are arranged independently of the positions of the contact sockets, such that the contact areas or the contact sockets can be adapted to the test base or to the test head or an intermediate board. The adapter board is therefore advantageously formed as a circuit board. The electrically conductive connection between the contact areas and the contact sockets is thus achieved via a well-tested and proven technique. Due to the formation of the adapter board as a circuit board, very cost-effective production is also possible.

The contact sockets are particularly advantageously inserted in blind bores in the adapter board. A feedthrough is thus avoided, and only the contact areas for the contact pins of the test base are provided on the side of the adapter board facing the test base. The adapter board can thus be formed

PATENT CLAIMS

1. A device for testing electronic components, comprising at least one test base ~~(13)~~ for contacting the electronic components ~~(17)~~ and comprising a test head, which is coupled electrically to the test base ~~(13)~~, characterised in that, in order to forward signals between the test base ~~(13)~~ and test head, an adapter board ~~(1)~~ is provided, which, on its side facing the test base ~~(13)~~, has contact areas ~~(2)~~ which are adapted to the position of contacts of the test base ~~(13)~~, and, on its side facing away from the test base ~~(13)~~, is provided with contact sockets ~~(4)~~ which are adapted to the position of contact pins ~~(10)~~ of the test head or of ~~an intermediate~~ a connection board ~~(6)~~, the contact areas ~~(2)~~ each being electrically conductively connected to corresponding contact sockets ~~(4)~~.

2. The device for testing electronic components according to Claim 1, characterised in that the positions of the contact areas ~~(2)~~ on one side of the adapter board ~~(1)~~ are arranged independently of the positions of the corresponding contact sockets ~~(4)~~ on the opposite side of the adapter board ~~(1)~~.

3. The device for testing electronic components according to one of Claims 1 to 2, characterised in that the adapter board ~~(1)~~ is formed as a circuit board.

4. The device for testing electronic components according to one of Claims 1 to 3, characterised in that the contact sockets ~~(4)~~ are inserted into blind bores ~~(3)~~ in the adapter board ~~(1)~~.

5. The device for testing electronic components according to one of Claims 1 to 4, characterised in that the contact sockets ~~(4)~~ are soldered to the adapter board ~~(1)~~.

6. The device for testing electronic components according to Claim 5, characterised in that the contact sockets ~~(4)~~ have an annular flange

~~(5)~~ and only the flange ~~(5)~~ is soldered to the surface of the adapter board ~~(1)~~.

7. The device for testing electronic components according to one of Claims 1 to 6, characterised in that ~~a~~ the connection board ~~(6)~~ is provided between the adapter board ~~(1)~~ and test head and comprises exchangeable contact pins ~~(10)~~ which protrude from the surface both from the side facing the adapter board ~~(1)~~ and from the side facing away from the test head.

8. The device for testing electronic components according to Claim 7, characterised in that the connection board ~~(6)~~ has two interconnected parts ~~(7, 8)~~ which can be separated from one another and reconnected in order to exchange the contact pins ~~(10)~~.

9. The device for testing electronic components according to one of Claims 7 to 8, characterised in that the connection board ~~(6)~~ has a temperature-insulating layer ~~(7)~~.

10. The device for testing electronic components according to one of Claims 7 to 9, characterised in that the connection board ~~(6)~~ can be flushed with air on its side facing the test head.